

Photocouplers Infrared LED & Photo Transistor

TLP387

1. Applications

- · Programmable Logic Controllers (PLCs)
- · I/O Interface Boards
- · Home Electric Appliances

2. General

TLP387 is a photocoupler that consist of an infrared LED optically coupled to a darlington transistor. Housed in a SO6L (4 pin) package, it has a high noise immunity and a high insulation. With the high brakdown voltage between the collector and emitter, TLP387 is suitable in applications such as 100VDC output modules of programmable controllers.

3. Features

- (1) Collector-emitter voltage: 300 V (min)
- (2) Current transfer ratio: 1000 % (min) (@I_F = 1 mA, V_{CE} = 1 V)
- (3) Isolation voltage: 5000 Vrms (min)
- (4) Operating temperature range: -55 to 110 °C
- (5) Safety standards

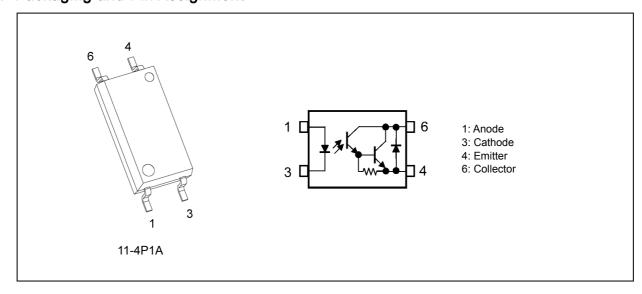
UL-recognized: UL 1577, File No.E67349

cUL-recognized: CSA Component Acceptance Service No.5A File No.E67349

VDE-approved: EN 60747-5-5, EN 62368-1 (Note 1) CQC-approved: GB4943.1, GB8898 Thailand Factory

Note 1: When a VDE approved type is needed, please designate the Option (D4).

4. Packaging and Pin Assignment





5. Mechanical Parameters

Characteristics	Min	Unit
Creepage distances	8.0	mm
Clearance	8.0	
Internal isolation thickness	0.4	

6. Absolute Maximum Ratings (Note) (Unless otherwise specified, Ta = 25 °C)

	Characteristics		Symbol	Note	Rating	Unit
LED	Input forward current		I _F		50	mA
	Input forward current derating	$(T_a \ge 90 ^{\circ}C)$	$\Delta I_F/\Delta T_a$		-1.43	mA/°C
	Input forward current (pulsed)		I _{FP}	(Note 1)	1	Α
	Input power dissipation		P_{D}		100	mW
	Input power dissipation derating	(T _a ≥ 90 °C)	$\Delta P_D/\Delta T_a$		-2.85	mW/°C
	Input reverse voltage		V_R		5	V
	Junction temperature		Tj		125	Ŝ
Detector	Collector-emitter voltage		V _{CEO}		300	V
	Emitter-collector voltage		V _{ECO}		0.3	
	Collector current		Ic		150	mA
	Collector power dissipation		P _C		150	mW
	Collector power dissipation derating	$(T_a \ge 25 ^{\circ}\text{C})$	$\Delta P_{C}/\Delta T_{a}$		-1.5	mW/°C
	Junction temperature		Tj		125	°C
Common	Operating temperature		T _{opr}		-55 to 110	°C
	Storage temperature		T _{stg}		-55 to 125	
	Lead soldering temperature	(10 s)	T _{sol}		260	
	Total power dissipation		P _T		250	mW
	Total power dissipation derating	$(T_a \ge 25 ^{\circ}C)$	$\Delta P_T/\Delta T_a$		-2.5	mW/°C
	Isolation voltage	A(C, 60 s, R.H. ≤ 60 %)	BV _S	(Note 2)	5000	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Pulse width (PW) \leq 0.1 ms, f = 1000 Hz

Note 2: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pin 4 and 6 are shorted together.



7. Electrical Characteristics (Unless otherwise specified, Ta = 25 °C)

	Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
LED	Input forward voltage	V _F		I _F = 10 mA	1.1	1.25	1.4	V
	Input reverse current	I _R		V _R = 5 V	_		10	μΑ
	Input capacitance	Ct		V = 0 V, f = 1 MHz	_	30	_	pF
Detector	Collector-emitter breakdown voltage	V _{(BR)CEO}		I _C = 0.1 mA	300			V
	Emitter-collector breakdown voltage	V _{(BR)ECO}		I _E = 0.1 mA	0.3			
	Dark Current	I _{DARK}		V _{CE} = 200 V	_	0.01	0.2	μА
				V _{CE} = 200 V, T _a = 85 °C			20	
	Collector-emitter capacitance	C _{CE}		V = 0 V, f = 1 MHz	_	10	_	pF

8. Coupled Electrical Characteristics (Unless otherwise specified, Ta = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Current transfer ratio	I _C /I _F		I _F = 1 mA, V _{CE} = 1 V	1000	4000		%
Saturated current transfer ratio	$I_C/I_{F(sat)}$		I _F = 10 mA, V _{CE} = 1 V	500			%
Collector-emitter saturation voltage	V _{CE(sat)}		I _C = 10 mA, I _F = 1 mA			1.0	V
			I _C = 100 mA, I _F = 10 mA	0.3	_	1.2	
OFF-state collector current	I _{C(off)}		V _F = 0.7 V, V _{CE} = 200 V	_		20	μА

9. Isolation Characteristics (Unless otherwise specified, Ta = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Total capacitance (input to output)	Cs	(Note 1)	V _S = 0 V, f = 1 MHz	_	0.6	_	pF
Isolation resistance	R _S	(Note 1)	V _S = 500 V, R.H. ≤ 60 %	10 ¹²	1014	_	Ω
Isolation voltage	BVS	(Note 1)	AC, 60 s	5000	_	_	Vrms

Note 1: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4 and 6 are shorted together.

10. Switching Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Rise time	t _r		V_{CC} = 10 V, I_{C} = 10 mA,	_	40		μS
Fall time	t _f		$R_L = 100 \Omega$	_	15		
Turn-on time	t _{on}			_	50	_	
Turn-off time	t _{off}			_	15	_	
Turn-on time	t _{on}		See Fig. 10.1	_	5	_	
Storage time	ts		$R_L = 180 \Omega$, $V_{CC} = 10 V$, $I_F = 16 \text{ mA}$	_	40	_	
Turn-off time	t _{off}		וון – זט ווויג	_	80		

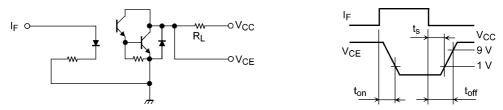
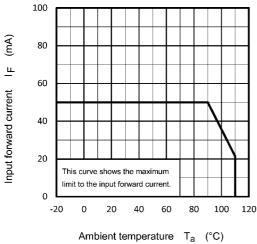
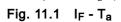


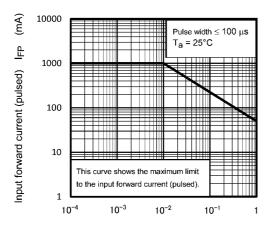
Fig. 10.1 Switching Time Test Circuit and Waveform



11. Characteristics Curves (Note)

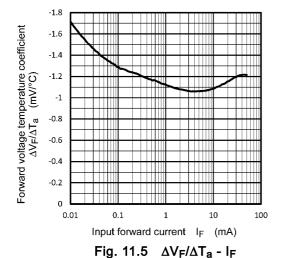


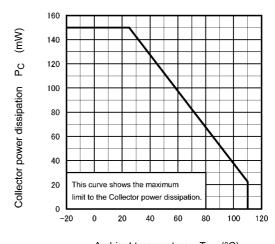




Duty cycle ratio D_R

Fig. 11.3 I_{FP} - D_R





Ambient temperature T_a (°C) Fig. 11.2 $P_C - T_a$

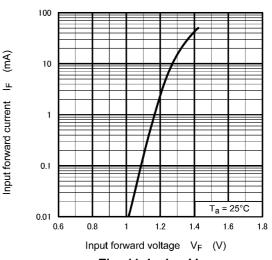


Fig. 11.4 I_F - V_F

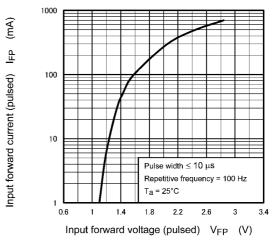


Fig. 11.6 I_{FP} - V_{FP}



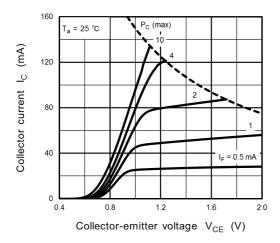


Fig. 11.7 I_C - V_{CE}

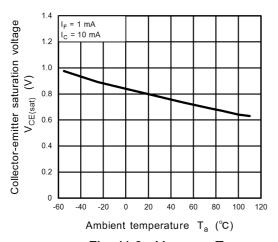


Fig. 11.9 V_{CE(sat)} - T_a

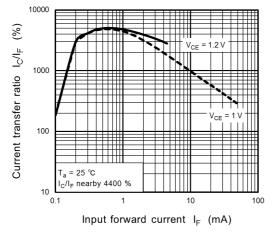


Fig. 11.11 I_C/I_F - I_F

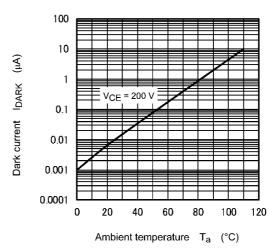


Fig. 11.8 IDARK - Ta

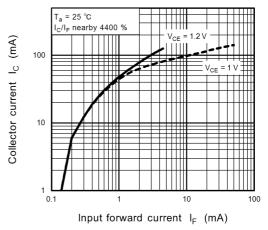


Fig. 11.10 I_C - I_F

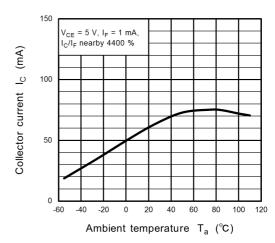


Fig. 11.12 I_C - T_a

Rev.3.0



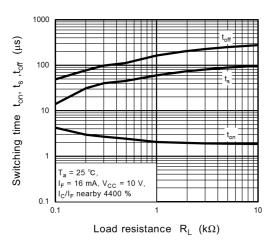


Fig. 11.13 Switching Time - RL

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



12. Soldering and Storage

12.1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

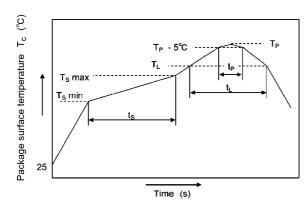
· When using soldering reflow.

The soldering temperature profile is based on the package surface temperature.

(See the figure shown below, which is based on the package surface temperature.)

Reflow soldering must be performed once or twice.

The mounting should be completed with the interval from the first to the last mountings being 2 weeks.



	Symbol	Min	Max	Unit
Preheat temperature	Ts	150	200	°C
Preheat time	ts	60	120	s
Ramp-up rate (T _L to T _P)			3	°C/s
Liquidus temperature	TL	2	17	°C
Time above T _L	t∟	60	150	s
Peak temperature	T _P		260	°C
Time during which T_c is between $(T_P - 5)$ and T_P	t _P		30	s
Ramp-down rate (T _P to T _L)			6	°C/s

An Example of a Temperature Profile When Lead(Pb)-Free Solder Is Used

· When using soldering flow

Preheat the device at a temperature of 150 $^{\circ}$ C (package surface temperature) for 60 to 120 seconds.

Mounting condition of 260 $^{\circ}$ C within 10 seconds is recommended.

Flow soldering must be performed once.

· When using soldering Iron

Complete soldering within 10 seconds for lead temperature not exceeding 260 °C or within 3 seconds not exceeding 350 °C

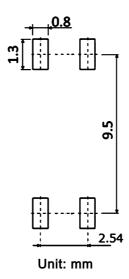
Heating by soldering iron must be done only once per lead.

12.2. Precautions for General Storage

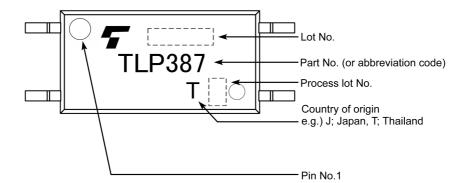
- · Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5 °C to 35 °C and 45 % to 75 %, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- · When restoring devices after removal from their packing, use anti-static containers.
- · Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.



13. Land Pattern Dimensions (for reference only)



14. Marking





15. EN 60747-5-5 Option (D4) Specification

• Part number: TLP387 (Note 1)

• The following part naming conventions are used for the devices that have been qualified according to option (D4) of EN 60747.

Example: TLP387(D4-TPL,E

D4: EN 60747 option

TPL: Tape type (L direction)

E: [[G]]/RoHS COMPATIBLE (Note 2)

Note 1: Use TOSHIBA standard type number for safety standard application.

e.g., TLP387(D4-TPL,E → TLP387

Note 2: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

Description	Symbol	Rating	Unit
Application classification			
for rated mains voltage \leq 600 Vrms for rated mains voltage \leq 1000 Vrms		I-IV I-III	_
Climatic classification		55 / 110 / 21	_
Pollution degree		2	_
Maximum operating insulation voltage	VIORM	1500	Vpeak
Input to output test voltage, Method A $V_{pr} = 1.6 \times V_{IORM} \text{, type and sample test} \\ t_p = 10 \text{ s, partial discharge} < 5 \text{ pC}$	V _{pr}	2400	Vpeak
Input to output test voltage, Method B $V_{pr} = 1.875 \times V_{IORM}, \ 100 \ \% \ production \ test$ $t_p = 1 \ s, \ partial \ discharge < 5 \ pC$	V _{pr}	2813	Vpeak
Highest permissible overvoltage (transient overvoltage, t _{pr} = 60 s)	VTR	8000	Vpeak
Safety limiting values (max. permissible ratings in case of fault, also refer to thermal derating curve) current (input current I_F , P_{SO} = 0) power (output or total power dissipation) temperature	I _{si} P _{so} T _s	250 400 150	mA mW °C
Insulation resistance V_{IO} = 500 V, T_a = 25 °C V_{IO} = 500 V, T_a = 100 °C V_{IO} = 500 V, T_a = T_S	R _{si}	≥ 10 ¹² ≥ 10 ¹¹ ≥ 10 ⁹	Ω

Fig. 15.1 EN 60747 Insulation Characteristics



Table 15.1 Insultion Related Specifications (Note)

Insulation Related Specification	Symbol	TLP387
Minimum creepage distance	Cr	8.0 mm
Minimum clearance	CI	8.0 mm
Minimum insulation thickness	ti	0.4 mm
Comparative tracking index	CTI	500

Note: This photocoupler is suitable for **safe electrical isolation** only within the safety limit data. Maintenance of the safety data shall be ensured by means of protective circuits.



Fig. 15.2 Marking on Packing

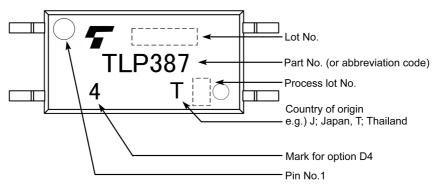
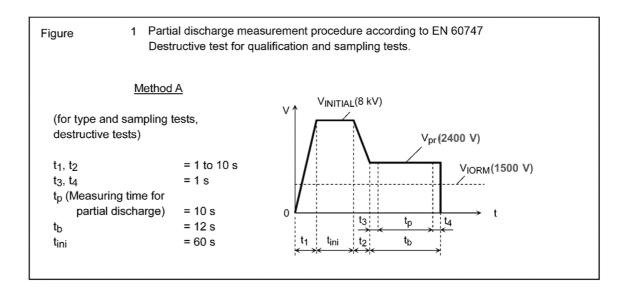
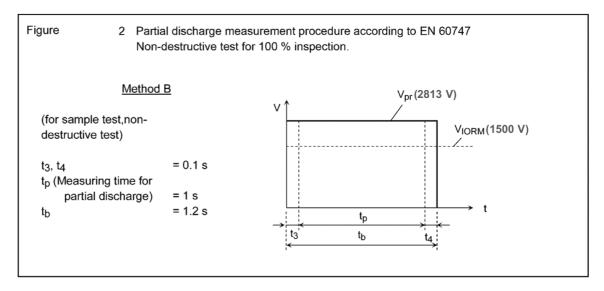


Fig. 15.3 Marking Example (Note 1)

Note 1: The above marking is applied to the photocouplers that have been qualified according to option (D4) of EN 60747.







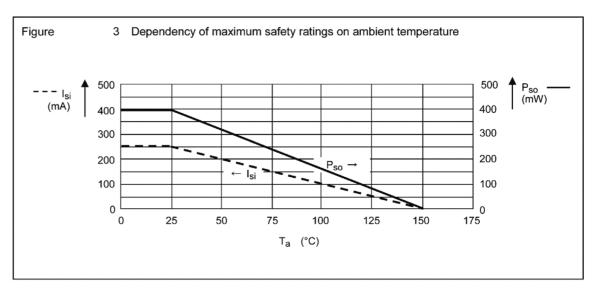


Fig. 15.4 Measurement Procedure

16. Ordering Information



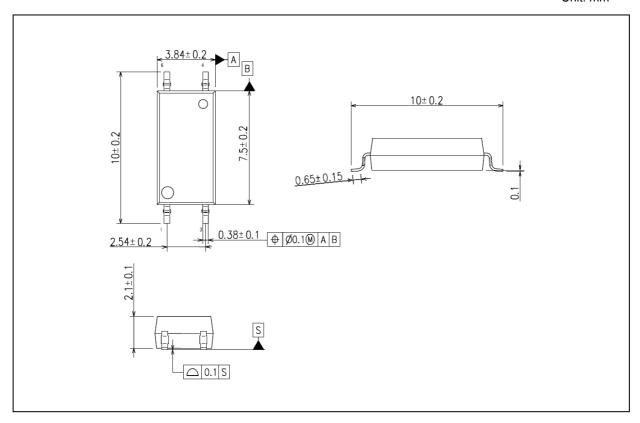
Note 1: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.



Package Dimensions

Unit: mm



Weight: 0.128 g (typ.)

	Package Name(s)
TOSHIBA: 11-4P1A	



RESTRICTIONS ON PRODUCT USE

Toshiba Corporation and its subsidiaries and affiliates are collectively referred to as "TOSHIBA". Hardware, software and systems described in this document are collectively referred to as "Product".

- · TOSHIBA reserves the right to make changes to the information in this document and related Product without notice.
- This document and any information herein may not be reproduced without prior written permission from TOSHIBA. Even with TOSHIBA's
 written permission, reproduction is permissible only if reproduction is without alteration/omission.
- Though TOSHIBA works continually to improve Product's quality and reliability, Product can malfunction or fail. Customers are responsible for complying with safety standards and for providing adequate designs and safeguards for their hardware, software and systems which minimize risk and avoid situations in which a malfunction or failure of Product could cause loss of human life, bodily injury or damage to property, including data loss or corruption. Before customers use the Product, create designs including the Product, or incorporate the Product into their own applications, customers must also refer to and comply with (a) the latest versions of all relevant TOSHIBA information, including without limitation, this document, the specifications, the data sheets and application notes for Product and the precautions and conditions set forth in the "TOSHIBA Semiconductor Reliability Handbook" and (b) the instructions for the application with which the Product will be used with or for. Customers are solely responsible for all aspects of their own product design or applications, including but not limited to (a) determining the appropriateness of the use of this Product in such design or applications; (b) evaluating and determining the applicability of any information contained in this document, or in charts, diagrams, programs, algorithms, sample application circuits, or any other referenced documents; and (c) validating all operating parameters for such designs and applications.

 TOSHIBA ASSUMES NO LIABILITY FOR CUSTOMERS' PRODUCT DESIGN OR APPLICATIONS.
- PRODUCT IS NEITHER INTENDED NOR WARRANTED FOR USE IN EQUIPMENTS OR SYSTEMS THAT REQUIRE EXTRAORDINARILY HIGH LEVELS OF QUALITY AND/OR RELIABILITY, AND/OR A MALFUNCTION OR FAILURE OF WHICH MAY CAUSE LOSS OF HUMAN LIFE, BODILY INJURY, SERIOUS PROPERTY DAMAGE AND/OR SERIOUS PUBLIC IMPACT ("UNINTENDED USE").
 - Except for specific applications as expressly stated in this document, Unintended Use includes, without limitation, equipment used in nuclear facilities, equipment used in the aerospace industry, lifesaving and/or life supporting medical equipment, equipment used for automobiles, trains, ships and other transportation, traffic signaling equipment, equipment used to control combustions or explosions, safety devices, elevators and escalators, and devices related to power plant.
 - IF YOU USE PRODUCT FOR UNINTENDED USE, TOSHIBA ASSUMES NO LIABILITY FOR PRODUCT.

For details, please contact your TOSHIBA sales representative or contact us via our website.

- · Do not disassemble, analyze, reverse-engineer, alter, modify, translate or copy Product, whether in whole or in part.
- Product shall not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any
 applicable laws or regulations.
- The information contained herein is presented only as guidance for Product use. No responsibility is assumed by TOSHIBA for any infringement of patents or any other intellectual property rights of third parties that may result from the use of Product. No license to any intellectual property right is granted by this document, whether express or implied, by estoppel or otherwise.
- ABSENT A WRITTEN SIGNED AGREEMENT, EXCEPT AS PROVIDED IN THE RELEVANT TERMS AND CONDITIONS OF SALE
 FOR PRODUCT, AND TO THE MAXIMUM EXTENT ALLOWABLE BY LAW, TOSHIBA (1) ASSUMES NO LIABILITY WHATSOEVER,
 INCLUDING WITHOUT LIMITATION, INDIRECT, CONSEQUENTIAL, SPECIAL, OR INCIDENTAL DAMAGES OR LOSS,
 INCLUDING WITHOUT LIMITATION, LOSS OF PROFITS, LOSS OF OPPORTUNITIES, BUSINESS INTERRUPTION AND LOSS
 OF DATA, AND (2) DISCLAIMS ANY AND ALL EXPRESS OR IMPLIED WARRANTIES AND CONDITIONS RELATED TO SALE,
 USE OF PRODUCT, OR INFORMATION, INCLUDING WARRANTIES OR CONDITIONS OF MERCHANTABILITY, FITNESS FOR
 A PARTICULAR PURPOSE, ACCURACY OF INFORMATION, OR NONINFRINGEMENT.
- GaAs (Gallium Arsenide) is used in Product. GaAs is harmful to humans if consumed or absorbed, whether in the form of dust or vapor.
 Handle with care and do not break, cut, crush, grind, dissolve chemically or otherwise expose GaAs in Product.
- Do not use or otherwise make available Product or related software or technology for any military purposes, including without limitation, for the design, development, use, stockpiling or manufacturing of nuclear, chemical, or biological weapons or missile technology products (mass destruction weapons). Product and related software and technology may be controlled under the applicable export laws and regulations including, without limitation, the Japanese Foreign Exchange and Foreign Trade Law and the U.S. Export Administration Regulations. Export and re-export of Product or related software or technology are strictly prohibited except in compliance with all applicable export laws and regulations.
- Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.
 Please use Product in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. TOSHIBA ASSUMES NO LIABILITY FOR DAMAGES OR LOSSES OCCURRING AS A RESULT OF NONCOMPLIANCE WITH APPLICABLE LAWS AND REGULATIONS.

TOSHIBA ELECTRONIC DEVICES & STORAGE CORPORATION

https://toshiba.semicon-storage.com/

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Transistor Output Optocouplers category:

Click to view products by Toshiba manufacturer:

Other Similar products are found below:

LTV-814S-TA LTV-824HS LTV-852S 66095-001 MCT6-X007 MOC8101-X017T PS2561-1-A PS2561A-1-W-A PS2561B-1-L-A PS2561L-1-V-A MRF658 IL755-1X007 ILD74-X001 ILQ615-3X016 LDA102S LDA110S SFH615AGR-X007T PS2561-1-V-W-A PS2561AL-1-V-A PS2561L1-1-L-A PS2701A-1-F3-P-A PS2801-1-F3-P-A PS2911-1-L-AX CNY17-4X001 CNY17-4X017 CNY17F-1X007 CNY17F-2X017 CNY17F-4X001 CNY17G-1 LTV-214 LTV-702V LTV-702VB LTV-733S LTV-816S-TA LTV-825S TCET2100 TLP187(TPL,E(T 4N25-X007T IL215AT ILD615-1X007 ILQ2-X007 VOS615A-2T WPPC-A11066AA WPPC-A11066AD WPPC-A11084ASS WPPC-A21068AA WPPC-D11066AA WPPC-D21068ED WPPC-D410616EA WPPC-D410616ED